

Product Change Notice

Date: 5/6/2015

Change: Wafer Size is changing from 5" to 6" on identified products

The purpose of this correspondence is to provide communication that IR HiRel has received notification of Vishay Semiconductors intent to change their silicon wafer diameter from 5 inches (125 mm) to 6 inches (150 mm) and manufacturing process to be adapted to 6" existing lines. This raw material is used on various products, as identified in the table below.

Die part	Description	Product
C000382H	HEXFRED, 600V, 240A	G200SPCK06P3F
C000462B	DIODE, FRED, 600V, 100A	G450HHBK06P2P
		G450HHBK06P2H
		G150SPBK06P3H
		G150SPBK06P3P
		G600HHGX06P2H
		G200SPCK06P3F

IR HiRel has received an initial lot of material from the updated process, and we have successfully completed Element Evaluation testing (Class H) on samples from this lot. This change is not expected to result in any performance impact on the products listed.

Should you have any further questions regarding this matter, please contact your IR Hi Rel Customer Service representative

Andrew Boisvert
QA Manager

PMM HiRel

An Infineon Technologies Company